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Jin-Su Ko; Bon-Kee Kim; Kwyro Lee;

Electron Devices, IEEE Transactions on , Volume: 44 , Issue: 5 , May 1997

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3 Simulating RF circuits using PSpice

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Pages: 10/1 - 10/5

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4 Accurate power supply and ground plane pair models [for MCMs]

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[PDF Full-Text (268 KB)] Abstract1

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 $\cdot$ 5 Æxtraction of accurate package models from VNA measurements